

ABSTRACT

The present disclosure provides a reaction chamber and semiconductor processing equipment. The reaction chamber includes an insulating chamber, a first heating body, a second heating body, and an isolation protection structure. The first heating body and the second heating body are arranged at an interval within the insulating chamber. The second heating body is provided with a carrier device for carrying a wafer. The isolation protection structure is arranged within the insulating chamber, located between the first heating body and the second heating body, forms a reaction space, and isolates the first heating body and the second heating body from the reaction space. An opening is arranged on a side of the isolation protection structure close to the second heating body, and the surface of the carrier device is exposed in the reaction space. In the technical solution of the reaction chamber and the semiconductor processing equipment of the present disclosure, the by-product attached to the heating body can be reduced, the equipment maintenance efficiency can be improved, and the equipment maintenance cost can be reduced.

FIG. 3A